

**CBRHD-01**  
**SURFACE MOUNT SILICON**  
**HIGH DENSITY**  
**0.8 AMP**  
**BRIDGE RECTIFIER**



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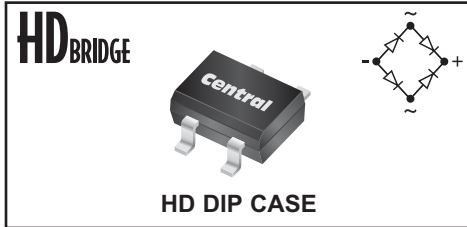
**DESCRIPTION:**

The CENTRAL SEMICONDUCTOR CBRHD-01 is a silicon full wave bridge rectifier mounted in a durable epoxy surface mount molded case, utilizing glass passivated chips.

**MARKING CODE: CBD1**

**FEATURES:**

- Efficient use of board space: requires only 42mm<sup>2</sup> of board space vs. 120mm<sup>2</sup> of board space needed for industry standard 1.0 Amp surface mount bridge rectifier.
- 50% higher density (Amps/mm<sup>2</sup>) than the industry standard 1.0 Amp surface mount bridge rectifier.
- Glass passivated chips for high reliability.



**MAXIMUM RATINGS:** (T<sub>A</sub>=25°C unless otherwise noted)

	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	100	V
DC Blocking Voltage	V <sub>R</sub>	100	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	70	V
Average Forward Current (T <sub>A</sub> =40°C) (Note 1)	I <sub>O</sub>	0.5	A
Average Forward Current (T <sub>A</sub> =40°C) (Note 2)	I <sub>O</sub>	0.8	A
Peak Forward Surge Current	I <sub>FSM</sub>	30	A
Operating and Storage Junction Temperature	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C
Thermal Resistance (Note 3)	θ <sub>JA</sub>	85	°C/W

**ELECTRICAL CHARACTERISTICS PER DIODE:** (T<sub>A</sub>=25°C unless otherwise noted)

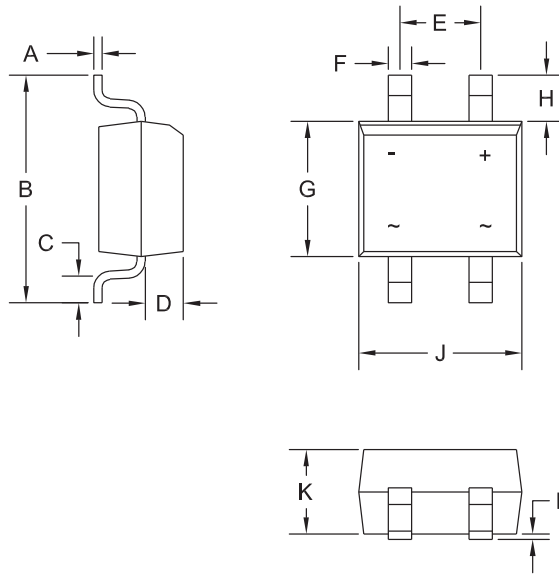
SYMBOL	TEST CONDITIONS	TYP	MAX	UNITS
I <sub>R</sub>	V <sub>R</sub> = 100V		5.0	μA
I <sub>R</sub>	V <sub>R</sub> = 100V, T <sub>A</sub> =125°C		500	μA
V <sub>F</sub>	I <sub>F</sub> =400mA		1.0	V
C <sub>J</sub>	V <sub>R</sub> =4.0V, f=1.0MHz	9.0		pF

- Notes: (1) Mounted on Glass-Epoxy PCB.  
(2) Mounted on Ceramic PCB.  
(3) Mounted on PCB with 0.5" x 0.5" copper pads.

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**HD DIP CASE - MECHANICAL OUTLINE**



R2

<b>DIMENSIONS</b>				
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.006	0.014	0.15	0.35
B	-	0.275	-	7.00
C	0.027	0.043	0.70	1.10
D	0.035	0.051	0.90	1.30
E	0.090	0.106	2.30	2.70
F	0.019	0.031	0.50	0.80
G	0.150	0.165	3.80	4.20
H	0.051	0.067	1.30	1.70
J	0.177	0.193	4.50	4.90
K	0.090	0.106	2.30	2.70
L	0.000	0.008	0.00	0.20

HD DIP (REV: R2)

**MARKING CODE: CBD1**

R3 (22-August 2016)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### CONTACT US

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